



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 183 E7764		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000740722						
<b>Package</b>		PG-SOT143-4-1		<b>Weight*</b>		11.06 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.002	0.02		163	
	non noble metal	tin	7440-31-5	0.000	0.00		42	
	inorganic material	silicon	7440-21-3	0.013	0.12	0.14	1209	1414
leadframe	non noble metal	nickel	7440-02-0	1.673	15.12		151232	
	non noble metal	iron	7439-89-6	2.310	20.88	36.00	208844	360076
wire	noble metal	gold	7440-57-5	0.016	0.14	0.14	1420	1420
encapsulation	organic material	carbon black	1333-86-4	0.104	0.94		9441	
	inorganic material	antimonytrioxide	1309-64-4	0.157	1.42		14162	
	plastics	brominated resin	-	0.196	1.77		17703	
	plastics	epoxy resin	-	1.632	14.75		147521	
	inorganic material	silicondioxide	60676-86-0	4.438	40.14	59.02	401256	590083
leadfinish	non noble metal	tin	7440-31-5	0.217	1.96	1.96	19584	19584
plating	noble metal	silver	7440-22-4	0.303	2.74	2.74	27423	27423
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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